

Title (en)
IMPROVED POWER SUPPLY TRANSIENT PERFORMANCE (POWER INTEGRITY) FOR A PROBE CARD ASSEMBLY IN AN INTEGRATED CIRCUIT TEST ENVIRONMENT

Title (de)
VERBESSERTE LEISTUNG VON TRANSIENTER STROMVERSORGUNG (STROMINTEGRITÄT) FÜR EINE SONDENKARTENANORDNUNG IN EINER TESTUMGEBUNG EINER INTEGRIERTEN SCHALTUNG

Title (fr)
PERFORMANCE TRANSITOIRE AMÉLIORÉ D'ALIMENTATION ÉLECTRIQUE (INTÉGRITÉ ÉLECTRIQUE) POUR UN ENSEMBLE CARTE SONDE DANS UN ENVIRONNEMENT DE TEST DE CIRCUIT INTÉGRÉ

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Application
EP 16803876 A 20160226

Priority
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Abstract (en)
[origin: WO2016195766A1] The present invention describes essentially three different embodiments for the implementation of low impedance (over frequency) power delivery to a die. Such low impedance to a high frequency allows the die to operate at package-level speed, thus reducing yield loss at the packaging level. Each embodiment addresses a slightly different aspect of the overall wafer probe application, lit each embodiment, however, the critical improvement of this disclosure is the location of the passive components used, for supply filtering/ decoupling relative to prior art. All three embodiments, require a method to embed the passive components in close proximity to the pitch translation substrate or physically in the pitch translation substrate.

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Citation (search report)
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